

IN THE CLAIMS:

Please amend Claims 1, 7 and 8 as shown below.

1. (Currently Amended) A printed wiring board comprising:  
a substrate having two opposite surfaces and a plurality of soldering through holes formed in said substrate;  
wherein each of said plurality of soldering through holes opens in said opposite surfaces for inserting leads of an inserted component to be mounted onto the printed wiring board and soldering said leads of an inserted component onto said substrate,  
wherein each of said plurality of soldering through holes has an inner peripheral surface and a pair of lands each formed continuously across said opposite surfaces therewith and the inner peripheral surface of a corresponding each of said plurality of soldering through holes,  
(1) wherein at least one land of said pair of lands is connected to at least one wiring pattern at a connection portion;  
said printed wiring board further comprising:  
connection state maintaining means for maintaining said a connection portion between the surface of each of said lands to which said wiring pattern is connected and said wiring pattern in a state not wetted by solder and for maintaining said at least one land of said pair of lands printed wiring board, except for said connection portion, in a state wetted by solder.

2. (Cancelled)

3. (Previously Amended) A printed wiring board as claimed in claim 1, wherein said connection state maintaining means comprises a material not wetted by the solder coated onto said pair of lands.

4. (Original) A printed wiring board as claimed in claim 3, wherein the material not wetted by the solder is a solder resist.

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Cont*

5. (Previously Amended) A printed wiring board as claimed in claim 3, wherein the material not wetted by the solder is a silk-screen pattern.

6. (Previously Amended) A printing wiring board as claimed in claim 3, wherein the material not wetted by the solder comprises a solder resist and a silk-screen pattern laminated onto each other.

7. (Currently Amended) A printed wiring board as claimed in claim 1, wherein said connection state maintaining means comprises deactivation treatment means for oxidizing at least a part of the surface of at least one land of said pair of lands.

8. (Currently Amended) A printed wiring board as claimed in claim 1, wherein lead solder is applied to the leads of the inserted component prior to insertion of  
*to said through holes of said printed wiring board.*  
*said leads of the inserted component.]*

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9. (Original) A printed wiring board as claimed in claim 1, wherein the inserted component is soldered onto said substrate by flow soldering using lead-free solder.

10. (Previously Amended) A printed wiring board as claimed in claim 9, wherein the lead-free solder contains Bismuth.

11. (Cancelled)

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